

**AB-0013:
SPICE Models for the
IAM- 81 and IAM-82 Active Mixers
Revised February, 1999****Introduction**

SPICE models provide the designer with insight into the non-linear behavior and bias dependence of semiconductor devices. This Bulletin presents the SPICE models for Hewlett-Packard's IAM-81 and IAM-82 active mixer product families.

Simulation Accuracy

At the outset, a few words on the accuracy of SPICE predictions are in order. SPICE (Simulation Program with Integrated Circuit Emphasis) is the generic name for a number of time based non-linear simulators based on the original Berkeley SPICE of 1973. SPICE has become the accepted non-linear modeling tool of the analog IC design community, and in general SPICE simulations give good insight into how a circuit will perform.

SPICE is not, however, a perfect depiction of reality. Simplifications in design models and limitations in the simulator can lead to significant discrepancies between prediction and measured results. In particular, problems with accuracy have been encountered when saturated devices are simulated, for example in simulations with low values of V_{cc} or simulations at extreme temperatures. RF performance over temperature is not well modeled in SPICE. Self heating effects can be important, and simulation temperatures should be adjusted accordingly, especially for higher dissipation parts such as the IAM-82 mixers. A correct description of external parasitics, and in particular of the ground path, is essential if SPICE predictions are to correlate with reality. In summary, a SPICE simulation should be viewed as a way of predicting trends and directions, and in no way substitutes for actual measurements on physical parts.

IAM-81 and IAM-82

The IAM-81 and IAM-82 are Gilbert multiplier active mixers manufactured using Hewlett-Packard's ISOSAT™ silicon MMIC process. Products based on these two designs can accept RF and LO signals up to 5 GHz, and provide gain with IF frequencies up to 1 GHz for the IAM- 81 and 2 GHz for the IAM-82. The IAM-81 mixers have a P_1 dB of -6 dBm, while the IAM-82 mixers have a P_1 dB of +8 dBm. More information on the IAM series products can be obtained in Applications Notes AN-SO10: A 5 GHz Bipolar Active Mixer and AN-SO13: MagIC™ Active Mixers.

The IAM81 and IAM82 mixers are offered in a number of packages. IAM-81000 and IAM-82000 are chip form; IAM-81008 and IAM-82008 are SO-8 plastic packaged versions, and IAM-81028 and IAM-82028 are glass-metal packaged devices. [Note: The IAM-82000 and IAM-82000 are obsolete products no longer offered for sale.]

SPICE Models

The IAM-81 and IAM-82 active mixers were designed using PSPICE, a variant of the original Berkeley SPICE program. These design models are reproduced below. Figures 1 and 2 present the models for the IAM-81 and IAM-82 mixers respectively. The equivalent circuits shown contain a description of the MMIC chip, of the packaging around the chip,

and of external circuit elements such as signal sources and bias networks. The values for the circuit components are given in Tables 1 and 2.

The solid (black) nodes in the Figures correspond to the node numbers in the simulations. Node 0 is reserved for hard ground. Note that a correct description of the path between the die substrate (node 100) and system ground (node 0) is critical for proper simulation results.

Chip Model

The MMIC chip description consists of an equivalent circuit that presented schematically, and transistor descriptions that appear as tables of parameter values. The boundaries of the chip are denoted in the Figures by hollow (white) circles. These circles correspond to the chip bond pads. Each bond pad is also labeled in square brackets (e.g. "[Vcc]") for easy identification.

The designed MIMIC consists of resistors and transistors. The resistors are all polysilicon, and have a temperature coefficient of $TC_1 = -8E-04$. Process tolerances allows a $\pm 10\%$ variation from lot to lot on resistor value, though tracking within a lot is typically $\pm 1\%$.

On-chip parasitic capacitances resulting from the metal interconnects on the die are not shown in the equivalent circuit, but are included in the tables of elements. Parasitic capacitors are given a name corresponding to the node number they are

associated with; i.e. C3 represents the capacitance between node 3 and the substrate (node 100).

The active transistors are described by sets of SPICE parameters. These descriptions are given in Table 3. This table presents a 'library' of devices used to make both the IAM-81 and the IAM-82 mixers. The transistor name gives pitch, number of emitter fingers, and emitter finger length. Four micron pitch transistors are used for the high frequency signal processing; eight micron pitch devices are used as biasing elements. Because of the number of transistors in the design, the 'spread base' description used in the catalog for discrete transistors is not used in the models of the active mixers - the resulting simulations would be excessively complex.

A deficiency of SPICE is that R does not predict the variation in RC with VCE seen in actual devices; instead it uses a single value from the SPICE parameter tables. To mitigate this effect, two values of RC are listed in Table 3: one for 5V operation (IAM-81) and one for 10 V operation (IAM-82).

Package Description

The equivalent circuits in Figures 1 and 2 include a number of elements labeled "pkg". These elements represent the physical path between the semiconductor chip and the circuit. Included in this path are such elements as bond wire inductances, MOS capacitors used with the chip, and package parasitics. These elements vary with package style, and can radically effect simulation predictions.

A generic package model is given in Figure 4. Element values corresponding to the 08 plastic SO-8 package, the 28 ceramic package and the 00 chip version are listed in Table 4. In general the inductors next to the die represent bond wires, and the inductors away from the die represent package lead inductance (omitted from the chip description). C5, C7, and C9 represent MOS capacitors used with the chip that are internal to the 08 and 28 packages, and must be supplied by the user when working with the 00 die. C5 bypasses the DC line; C7 and C9 provide AC ground references to the low side of the RF and LO ports respectively. Hewlett-Packard uses 150 pF

capacitors for each of these elements. The remaining capacitors represent package parasitics.

External Circuitry

The equivalent circuits include such off-chip elements as AC signal sources and bias networks. These elements are required by the SPICE simulation, but will vary in value from simulation to simulation to fit device usage. The values listed are what was used in the design files, and represent ideal connections of signal sources to the packaged chip. This description should be augmented with a description of the physical environment the mixer will be used in. Particularly critical are accurate descriptions of the ground path (e.g. vias) and the decoupling of the bias line. Cglo, Cgrf represent external capacitors used to AC ground the FIF and LO ports. These elements are mandatory with chip (00 package) use, but are only used to extend frequency range for the packaged devices. For more on extended low frequency use see AN-S013. Cvcc represents external bypassing on the bias line.

VCC is the DC power supply; the values shown in Tables 1 and 2 represent the recommended bias levels for the mixer being modeled. The AC signal sources are simply listed as "AC*", their characteristics will vary from simulation to simulation as they define the frequency and power level of the input signals to the mixer. Vout is a "dummy" generator used to measure output characteristics.

A sample PSPICE file for the IAM-81028 mixer is given in Figure 5. This simulation results in a model of the packaged device only; no circuit effects are included. When describing the use of the packaged MMIC in a real circuit, appropriate values would be provided for Cglo, Cgrf and Lvia. Values for blocking capacitors Clo, Crf and Cout would be adjusted to those used in the circuit. Generator and load impedances would be adjusted to reflect the circuit environment- this might include moderately detailed descriptions of the applications circuit. Vlo and Vrf sources would be adjusted to describe applied signals.

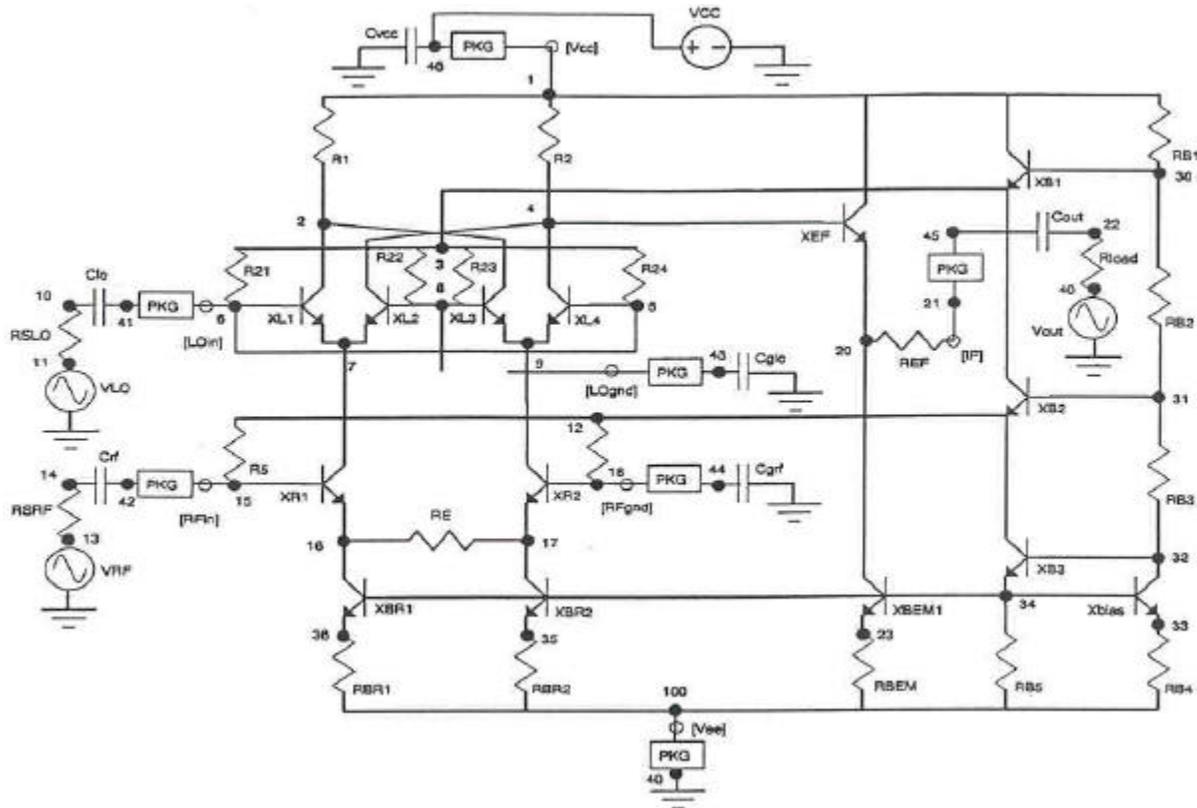


Figure 1. Equivalent Circuit for IAM-81 Active Mixer

Table 1. Equivalent Circuit Values for the IAM-81 Active Mixer

Transistors		Resistors		Parasitic Capacitors		External Components	
XR1	I40420	R1	400	C2	.05 pF	VLO	AC
XR2	I40420	R2	400	C3	.05 pF	RSLO	50
XL1	I40220	R3	50	C4	.08 pF	CLO	6800 pF
XL2	I40220	R4	50	C6	.11 pF	VRF	AC
XL3	I40220	R21	100	C7	.02 pF	RSRF	50
XL4	I40220	R22	100	C8	.02 pF	CRF	6800 pF
XEF	I40820	R23	100	C12	.07 pF	Vout	AC
XB1	I80220	R24	100	C15	.09 pF	Rload	50
XB2	I80220	RE	20	C16	.15 pF	Cout	6800 pF
XB3	I80220	REF	25	C17	.14 pF	Vcc	5 V DC
Xbias	I80220	RB1	800	C20	.05 pF	Cglo	user
XBR1	I80220	RB2	700	C21	.11 pF	Cgrf	user
XBR2	I80220	RB3	500	C23	.01 pF	Cvcc	user
XBEM1	I80420	RB4	200	C30	.05 pF	pkg	Table 4
		RB5	1000	C31	.03 pF		
		RBEM1	45	C32	.15 pF		
		RBR1	170	C33	.01 pF		
		RBR2	170	C34	.13 pF		

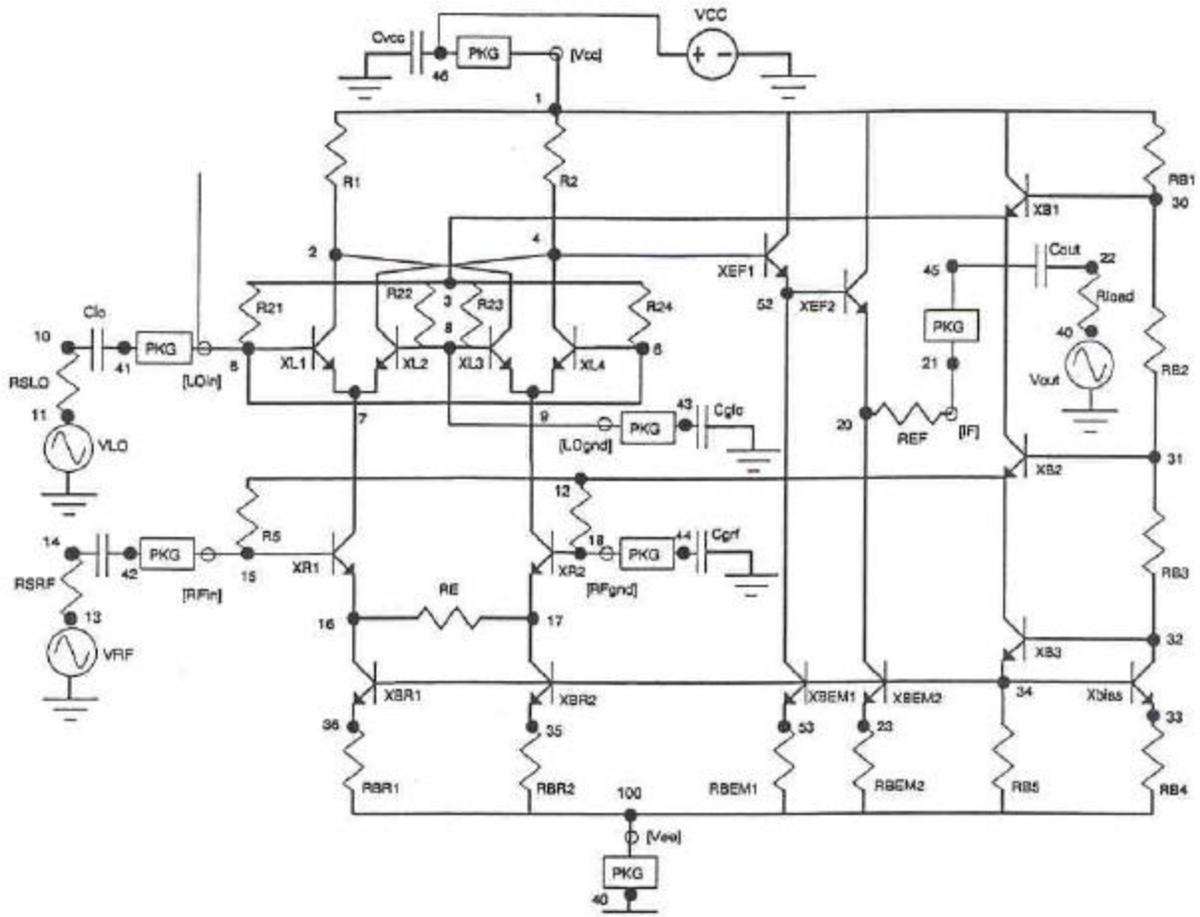


Figure 2. Equivalent Circuit for IAM-82 Active Mixer

Table 2. Equivalent Circuit Values for the IAM-82 Active Mixer

Transistors		Resistors		Parasitic Capacitors		External Components	
XR1	I40820	R1	700	C2	.05 pF	VLO	AC
XR2	I40820	R2	700	C3	.05 pF	RSLO	50
XL1	I40420	R3	50	C4	.08 pF	CLO	6800 pF
XL2	I40420	R4	50	C6	.11 pF	VRF	AC
XL3	I40420	R21	100	C7	.02 pF	RSRF	50
XL4	I40420	R22	100	C8	.02 pF	CRF	6800 pF
XEF1	I40420	R23	100	C12	.07 pF	Vout	AC
XEF2	I41620	R24	100	C15	.09 pF	Rload	50
XB1	I80420	RE	40	C16	.15 pF	Cout	6800 pF
XB2	I80420	REF	25	C17	.14 pF	Vcc	10 V DC
XB3	I80420	RB1	1260	C20	.05 pF	Cglo	user
Xbias	I80420	RB2	465	C21	.11 pF	Cgrf	user
XBR1	I80420	RB3	275	C23	.01 pF	Cvcc	user
XBR2	I80420	RB4	200	C30	.05 pF	pkg	Table 4
XBEM1	I80420	RB5	1000	C31	.03 pF		
XBEM2	I80820	RBEM1	100	C32	.15 pF		
		RBEM2	25	C33	.01 pF		
		RBR1	170	C34	.13 pF		
		RBR2	170	C52	.06 pF		

Table 3. SPICE transistor models for IAM -81 and IAM-82 Active Mixers

Parameter	I40220	I40420	I40820	I41620	I80220'	I80420	I80820
model	NPN						
BF	90	100	100	100	90	100	100
IS	7.9E-17	1.6E-16	3.2E-16	6.3E-16	9.6E-17	1.9E-16	3.8E-16
VA	20	20	20	20	20	20	20
BR	2.5	2.5	2.5	2.5	2.5	2.5	2.5
ME	0.6	0.6	0.6	0.6	0.6	0.6	0.6
NF	1.03	1.03	1.03	1.03	1.03	1.03	1.03
PTF	25	25	25	25	25	25	25
TF	1.2E-11						
CJE	1.2E-13	2.3E-13	4.6E-13	9.2E-13	1.4E-13	2.8E-13	5.6E-13
XTF	4	4	4	4	4	4	4
IK	6.4E-03	1.3E-02	2.6E-02	5.1E-02	7.7E-03	1.5E-02	3.1E-02
PE	1.01	1.01	1.01	1.01	1.01	1.01	1.01
ISE	2.4E-13	4.8E-13	9.6E-13	1.9E-12	2.9E-13	5.8E-13	1.2E-12
NE	2.5	2.5	2.5	2.5	2.5	2.5	2.5
VTF	6	6	6	6	6	6	6
XTB	1.818	1.818	1.818	1.818	1.818	1.818	1.818
ITF	1.4E-02	2.9E-02	5.8E-02	1.2E-01	1.7E-02	3.5E-02	7.0E-02
RB	58.47	29.42	14.78	7.59	90.24	44.69	22.40
RE	2.08	1.04	0.52	0.26	1.60	0.80	0.40
RC (5V)	81.45	59.90	31.62		95.27	27.63	
RC (10V)		20.83	29.73	13.64		13.64	14.61
CJC	6.1E-14	1.0E-13	1.9E-13	3.6E-13	1.0E-13	1.9E-13	3.6E-13
CJS	1.0E-13	1.3E-13	1.8E-13	2.8E-13	1.3E-13	1.8E-13	1.8E-13
XCJC	0.16	0.19	0.20	0.21	0.12	0.13	0.14
PS	0.80	0.80	0.80	0.80	0.80	0.80	0.80
MS	0.5	0.5	0.5	0.5	0.5	0.5	0.5
PC	0.76	0.76	0.76	0.76	0.76	0.76	0.76
MC	0.53	0.53	0.53	0.53	0.53	0.53	0.53

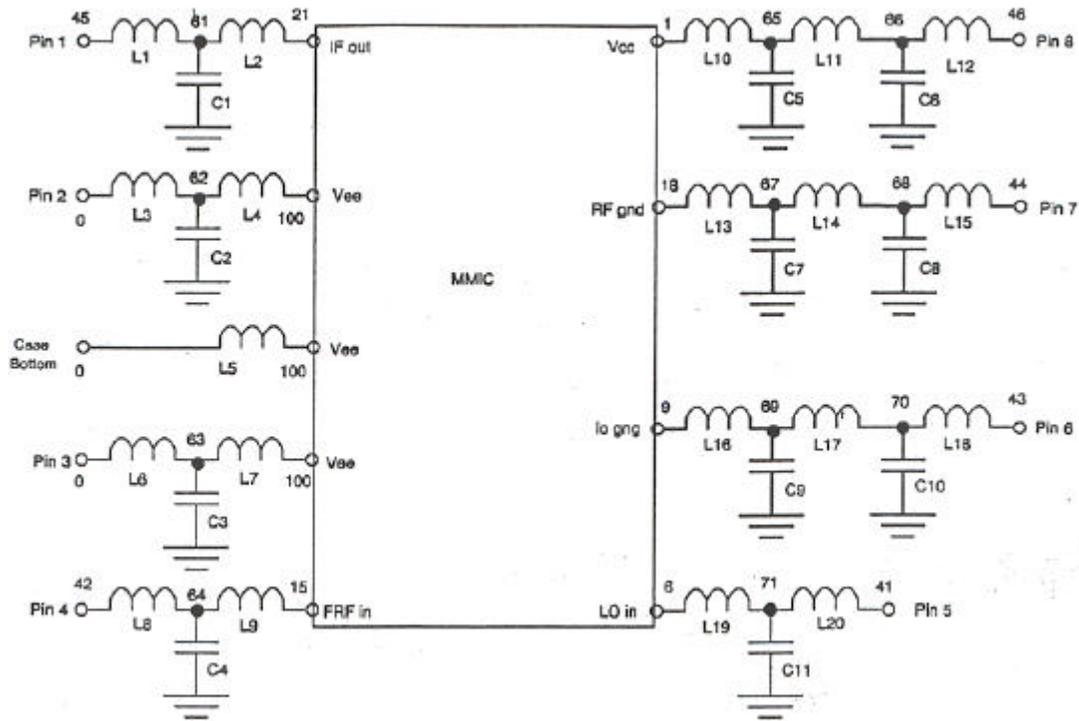


Figure 3. Package Equivalent Circuit

Table 4. Component Values for 00, 08 and 28 Package Models

Elements	Units	Chip (00)	SO-8 (08)	Ceramic (28)
L1	nH	-	1.8	1.5
L2	nH	0.8	0.8	0.8
C1	pF	-	0.2	0.2
L3	nH	-	1.8	1.5
L4	nH	-	0.6	0.6
C2	pF	-	0.2	0.2
L5	nH	0.15	-	0.25
L6	nH	-	1.8	1.5
L7	nH	-	0.6	0.6
C3	pF	-	0.2	0.2
L8	nH	-	1.8	1.5
L9	nH	0.8	0.8	0.8
C4	pF	-	0.2	0.2
L10	nH	0.4	0.4	0.4
L11	nH	-	0.4	0.4
L12	nH	-	1.8	1.5
C5	pF	-	150	150
C6	pF	-	0.2	0.2
L13	nH	0.4	0.4	0.4
L14	nH	-	0.4	0.4
L15	nH	-	1.8	1.5
C7	pF	-	150	150
C8	pF	-	0.2	0.2
L16	nH	0.4	0.4	0.4
L17	nH	-	0.4	0.4
L18	nH	-	1.8	1.5
C9	pF	-	150	150
C10	pF	-	0.2	0.2
L19	nH	1.0	1.0	1.0
L20	nH	-	1.8	1.5
C11	pF	-	0.2	0.2

Figure 5. PSPICE simulation of IAM-81028

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*IAM81.CIR **5 volt ISOSAT active mixer**
LIB IAM81.LIB
.OPTIONS LIMPTS 20001 ITL1=100 ITL2=100 ITL5=0 RELTOL=0.01 NOMOD
.Op
*EXTERNAL COMPONENTS SOURCES AND LOADS
VLO      11      0      0
VRF      13      0      0
VOUT     40      0      0
VCV      1       0      5
CLO      10      6      6800PF
CRF      14      15     6800PF
COUT     21      22     6800PF
CVCC     46      0      1000PF
RSLO     10      11     50
RSRF     14      13     50
RLOAD    40      22     50
*EXTERNAL ELEMENTS NOT USED FOR SIMULATION OF PKGD MMIC ONLY
CGLO     43      0      0.01PF
CGRF     44      0      0.01 PF
LVIA     48      0      0.01NH
* MMIC DESCRIPTION
RE       16      17      RPOLY  20
XRI      7       15     16     100    I40420
XR2      9       18     17     100    I40420
XL1      2       6      7      100    I40220
XL-2     4       8      7      100    I40220
XL-3     2       8      9      100    I40220
XL-4     4       6      9      100    I40220
XEF      1       4      20     100    I40820
XB1      1       30     3      100    I80220
XB2      3       31     12     100    I80220
XB3      12      32     34     100    I80220
XBIAS    32      34     33     100    I80220
XBR2     17      34     35     100    I80220
XBR1     16      34     36     100    I80220
XBEM     20      34     23     100    I80420
RB1      1       30     RPOLY  800
RB2      30      31     RPOLY  700
RB3      31      32     RPOLY  500
RB4      33      100    RPOLY  200
RBS      34      100    RPOLY  1000
RBR1     36      100    RPOLY  170
RBR2     35      100    RPOLY  100
RBEM     23      100    RPOLY  45
R1       1       2      RPOLY  400
R2       1       4      RPOLY  400
R21      3       6      RPOLY  100
R22      3       8      RPOLY  100
R23      3       8      RPOLY  100
R24      3       6      RPOLY  100
REF      20      21     RPOLY  25
*CN=METAL OR POLY TO SUBSTRATE C ASSOCIATED WITH NODE N
C2       2       100    .05PF
C3       3       100    .05PF
C4       4       100    .08PF
O6       6       100    .11PF
O7       7       100    .02PF
C8       8       100    .02PF
C12      12      100    .07PF
C15      15      100    .09PF
C16      16      100    .15PF
C17      17      100    .14PF
C20      20      100    .05PF
C21      21      100    .11PF
C23      23      100    .01PF
C30      30      100    .05PF
C31      31      100    .03PF
C32      32      100    .15PF
C33      33      100    .01PF
C34      34      100    .13PF
*PACKAGE DESCRIPTION
L1       45      61     1.5NH
L2       61      21     0.8NH
CP1      61      0      0.2PF
L3       48      62     1.5NH
L4       62      100    0.6NH
CP2      62      0      0.2PF
L5       48      100    0.15NH
L6       48      63     1.5NH
L7       63      100    0.6NH
CP3      63      0      0.2PF
L8       42      64     1.5NH
L9       64      15     0.8NH
CP4      64      0      0.2PF

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L10      1       65     0.4NH
L11      65      66     0.4NH
L12      66      46     1.5NH
CP5      65      0      150PF
CP6      66      0      0.2PF
L13      18      67     0.4NH
L14      67      68     0.4NH
L15      68      44     1.5NH
CP7      67      0      150PF
CP8      68      0      0.2PF
L16      9       69     0.4NH
L17      69      70     0.4NH
L18      70      43     1.5NH
CP9      69      0      150PF
CP10     70      0      0.2NH
L19      6       71     1.0NH
L20      71      41     1.5NH
CP11     71      0      0.2PF
.END

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